

Cement-based levelling and smoothing compound

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Special features	reducing tensionvery good flow propertieseasy to sand
Application range	✓ suitable below Vinyl, elastic/textile floor coverings and wood flooring
Suitable sub floors	 sanded mastic asphalt screed concrete C 25 / 30 according to DIN 1045 (non-skid surface) calcium sulphate (flow) floors Raised access floors wooden planks, wood fibre boards STAUF levelling compounds magnesite and plaster floors chipboards V100 (E1), OSB boards unlaminated gypsum fibre boards cement floors
Suitable primers	 STAUF Floorfix D 53 STAUF Floorfix D 63 STAUF Floorfix VEP 93
Product properties	 up to 1 mm suitable for chair rollers according to DIN EN 12529 suitable on sub floor heating systems pumpable very low emission
Color	✓ light grey
Consumption in g/m² per mm layer thickness	✓ 1600g per mm layer thickness
Accessibility/ready for foot traffic	✓ after 3 hours at 25°C, max 65% RH
Ready for installation	24 hours at 25°C, (with 2 mm layer thickness) max 65% RH
Room climate at work site	 minimum 15 °C, maximum 35°C maximum 75% RH, preferably max. 65%

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Transport requirements	✓ dry
Storage requirements	✓ dry
Shelf-life	√ 9 months
Available packaging	✓ 25 kg paper bag
layer thickness	 minimum 1 mm below floor coverings min. 2 mm below wood flooring maximum 10 mm mastic asphalt screed 2-5 mm
Processing time	✓ approx. 30 minutes at 25°C and 65% RH
Mixing ratio component A	 layer thickness up to 5 mm: 25 kg levelling compound layer thickness above 5 mm: 25 kg levelling compound
Mixing ratio component B	layer thickness up to 5 mm: 6 - 6.5 liter waterlayer thickness above 5 mm: 6 liter water



EXAMINATION OF SUBFLOOR

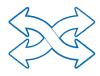
Before laying the covering, check the subfloor in accordance with DIN 18356 and DIN 18365. The subfloor shall be resistant to pressure and tension, free of cracks, must have sufficient surface strength, be permanently dry, level, clean and free of anti-adherents, sinter layers etc. In addition, porosity and grip of surface need to be checked. Also check moisture content and absorptive capacity of cement (flow) and calciumsulfate (flow) floors as well as room temperature, air humidity and sub floor temperature.



SUBFLOOR PREPARATION

It must be ensured that the subfloor is ready for installation by performing proper subfloor preparation, floors must be clean, have sufficient surface strength, must be level, permanently dry and free of cracks. A mechanical pretreatment of the subfloor (sweeping, vacuuming, mechanical brushing, sanding, milling, shot blasting) must be performed depending on type and condition of sub floor. Cracks and joints, except expansion joints and other construction joints, shall be solidly closed with STAUF casting resin and floor brackets. Cavities and indentations can be filled with a non self-levelling STAUF Floorfix levelling compound. In order to improve adhesion of adhesives and leveling compounds, prime the subfloor with the appropriate primer.





Add specified amount of water (clean and cold) into clean mixing bucket. Add complete content of container and stir evenly. For mixing, use an electrical stirrer with approx. 600 - 800 rpm with spiral or large paddle mixer. Mix until you have a homogeneous compound. Mix for another two minutes, wait one minute and then stir again for one minute (does NOT apply for non-self levelling compounds). For reinforced levelling compound: Add 1 pouch (250 g) STAUF reinforcement fibers after initial stirring and then stir again for 2 minutes.

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PROCESSING

Apply self-levelling compound within specified processing time. Do not pour the compound from mixing beaker on one spot only, but spread over a surface of approx. 2 x 2 m by changing position during pouring. Layer thickness can be controlled by using a wiper or a smoothing trowel. Air the levelling compound using a prickle roller. Self-levelling compounds do not require any additional mechanical spreading and form an even surface by themselves. Lower temperatures or higher ambient humidity delay the period until floor is ready for installation. The compound sets hydraulically, which means that it needs to be protected from direct sunlight and draughts. Before applying a further layer of filler or levelling compound, apply an intermediate layer of STAUF dispersion primer for filler compounds. Do not prime levelling and filler compounds before direct adhesion. For chipboard and OS panels, layer thicknesses of up to 5 mm are admissible. On less absorbent subfloors and under flexible coverings, layer thickness of at least 2 mm.



LIMITATION OF LIABILITY

The foregoing representations are based on the results of our most current product and material testing and are of a non-obligatory advisory nature only since we have no control over the actual quality of workmanship, materials used and worksite conditions. As such, they do not constitute an express or implied warranty of any kind. The same applies to our commercial and technical consultation services which are provided free-of-charge and without obligation. Therefore, we strongly recommend that prior onsite testing be conducted to observe and study the suitability of the product for the intended purpose. With the release of this technical information, all prior technical information (technical data sheets, installation recommendations and other information regarding similar purposes) becomes invalid.

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